



# 3D XE Series

Basic Line · 3D XE, Advanced Line · 3D XE



- cost-efficient 3D AOI system for stand-alone or inline use
- optimum solution for small and medium batch sizes
- dual use with full 3D SPI capability



Inspection parameters	Data	
	Basic Line · 3D XE, Advanced Line · 3D XE	
	Standard	High Resolution
x/y resolution	20 µm	15 µm
z resolution	1 µm	1 µm
height measuring range	13 mm	13 mm
component clearance above assembly	40 mm	40 mm
inspection speed	up to 50 cm <sup>2</sup> /s	up to 35 cm <sup>2</sup> /s

## Flexibility

- manual loading or inline integration
- alternate resolution versions
- full 3D SPI system
- expandable inspection area



## Test program generation and optimization

- fully automatic generation and optimization of test program and component library based on AI with MagicClick
- automatic parameter adjustment on the basis of sample assemblies and IPC specification

## Data import

- easy integration through import of numerous data formats
- convenient operation through dedicated data import module

## MES / Industry 4.0

- custom MES connection available with system delivery
- central defect verification for multiple inspection systems with PILOT Supervisor

## 3D XE Series

3D AOI, 3D SPI

## Economy efficiency

- attractive purchase price
- program generation and optimization time reduced by up to 80 %
- production ready 3D AOI process from the 2nd assembly



**IPC-HERMES-9852**  
The global standard for "M2M" in SMT assembly



Made in Germany

System parameters	Data	
	Basic Line · 3D XE	Advanced Line · 3D XE
inline interface	-	SMEMA, Siemens, Hermes, IPC CFX
max. inspection area	460 mm x 350 mm, optional up to 460 mm x 500 mm	410 mm x 450 mm, optional up to 1600 mm x 450 mm
dimension (WxDxH)	1133 mm x 1142 mm x 1420 mm	1000 mm x 1330 mm x 1500 mm
weight	490 kg	580 kg
energy demand	230 V AC / 1 kVA	230 V AC / 1,2 kVA; 6 bar compressed air